L Number	Hits	Search Text	DB	Time stamp
1	96	(substrate) near3 (bonding or mounting or	USPAT;	2003/01/24 08:53
_	"	attachment or attaching) near3 (eutectic or	US-PGPUB;	1003, 01, 21 00:33
	1	eutectoid)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
8	1654	eutectoid	USPAT;	2003/01/24 08:53
0	1034	Cutcetoia	US-PGPUB;	2000, 01, 21 00.33
			EPO; JPO;	
			DERWENT;	
	1		IBM TDB	
15	162	(substrate) near3 (bonding or mounting or	USPAT;	2003/01/24 09:00
		attachment or attaching) near6 (eutectic or	US-PGPUB;	
		eutectoid)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
22	0	(substrate) near3 (bonding or mounting or	USPAT;	2003/01/24 08:53
		attachment or attaching) near6 (eutectoid)	US-PGPUB;	
		"	EPO; JPO;	
			DERWENT;	
			IBM TDB	
29	11	(bonding or mounting or attachment or	USPAT;	2003/01/24 08:54
		attaching) near6 (eutectoid)	US-PGPUB;	
			EPO; JPO;	
		,	DERWENT;	
			IBM_TDB	
36	95	(substrate or die or chip or ic) near4	USPAT;	2003/01/24 09:08
		(bonding or mounting) and (adhesive or tape	US-PGPUB;	
		or epoxy) near4 (hole or perforation or cut	EPO; JPO;	
		or groove) near4 (vent or gas or air)	DERWENT;	
			IBM_TDB	
-	118	<u> </u>	USPAT;	2003/01/22 15:14
		(aligning or alignment or align or	US-PGPUB;	
		positioning or position or positioned or	EPO; JPO;	
		aligned or placed or placement or	DERWENT;	
		arrangement or placing or arranging or	IBM_TDB	
		arranged)		
-	10		USPAT;	2003/01/13 13:16
		circuit) near4 template near10 (aligning or	US-PGPUB;	
		alignment or align or positioning or	EPO; JPO;	
		position or positioned or aligned or placed	DERWENT;	
		or placement or arrangement or placing or	IBM_TDB	
		arranging or arranged)) and (mems or		
		micromirror or mirror)		
-	152		USPAT;	2003/01/13 13:21
		circuit) near4 template near10 (aligning or	US-PGPUB;	
		alignment or align or positioning or	EPO; JPO;	
		position or positioned or aligned or placed	DERWENT;	
		or placement or arrangement or placing or	IBM_TDB	
	0.5	arranging or arranged)	IICDATE -	2003/01/13 14:29
_	96	1,	USPAT;	2003/01/13 14:29
		circuit) near4 template and substrate and semiconductor	US-PGPUB; EPO; JPO;	
		Semicolludoror	DERWENT;	
			IBM_TDB	
_	733	(mems) and (die or dice or ic or mirror or	USPAT;	2003/01/13 14:42
	/33	micromirror) near3 (alignment or aligning or	US-PGPUB;	2003/01/13 14:42
		template or aligned or positioning or	EPO; JPO;	
		positioned or position or align or placement	DERWENT;	
		or location or locate or placing)	IBM TDB	
_	2568		USPAT;	2003/01/13 14:42
	2308	momo dia compiaco	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1		IBM TDB	
		mems and (mounting or mount-or alignment-or	USPAT;	2003/01/13 14:46
	211	aligning or align or aligned or positioning	US-PGPUB;	20009.017.13. 11.140.
		or position) near8 template	EPO; JPO;	
		or position, near compared	DERWENT;	
			IBM TDB	
	_ 	I		L

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-	44	mems! and (mounting or mount or alignment or aligning or align or aligned or positioning or position) near8 template	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/13 15:23
- -	2 125	("5824186" "6297072").PN. mems! and (mounting or mount or alignment or	IBM_TDB USPAT USPAT;	2003/01/13 15:17 2003/01/13 16:17
		aligning or align or aligned or positioning or position) near8 (substrate or wafer) near3 (recess or hole or divot or protrusion or projection or walls or indentation or indent)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
_	958	(alignment or aligning) near2 template	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/13 16:17
1	144	(mems and (mirror near2 arrays! or micromirror near2 arrays!)) and (bonding or placement or positioning or placing or mounting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/23 13:50
8	152	moems	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/23 13:57
15	1	(bonding or mounting) near6 adhesive near4 (groove or cut or perforation or vent) near5 gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/23 14:00
22	7	(bonding or mounting) with adhesive near6 (groove or cut or perforation or vent) near5 gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/23 14:02
29	2348	(bonding or mounting) with substrate near6 (groove or cut or perforation or vent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/23 14:03
36	37	(bonding or mounting) same substrate near6 (groove or cut or perforation or vent) near8 gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/23 14:09
43	858	(257/\$.ccls. or 438/\$.ccls.) and (mounting or bonding or adhering or bonded or mounted or adhesive or adhere) near4 (eutectic or eutectoid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/23 14:17
	2	(257/\$.ccls. or 438/\$.ccls.) and (mounting or bonding or adhering or bonded or mounted or adhesive or adhere) near4 (eutectic or eutectoid) near4 (parallel or tilt or flat	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/23 14:21
-	10	or bonding or adhering or bonded or mounted or adhesive or adhere) near4 (eutectic or eutectoid) and (eutectic or cutectoid) near8	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/01/23 15:52
_	858	(parallel or tilt or flat or flattened or flatness or tilted or uniform or uniformity) (257/\$.ccls. or 438/\$.ccls.) and (mounting or bonding or adhering or bonded or mounted or adhesive-or-adhere)—near4—(eutectic or-	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/01/23 15:54
		eutectoid)	DERWENT; IBM TDB	

-	108	(257/\$.ccls. or 438/\$.ccls.) and (mounting	USPAT;	2003/01/23 16:02
		or bonding or adhering or bonded or mounted	US-PGPUB;	
		or adhesive or adhere) and (substrate or	EPO; JPO;	
		wafer) near2 (perforations or holes or vents	DERWENT;	
		or depressions or groove) near4 (gas or	IBM_TDB	
		vent or venting or escape or escaping)		
-	19	(257/\$.ccls. or 438/\$.ccls.) and (mounting	USPAT;	2003/01/23 16:07
		or bonding or adhering or bonded or mounted	US-PGPUB;	
		or adhesive or adhere) and (adhesive) near2	EPO; JPO;	
		(perforations or holes or vents or	DERWENT;	
		depressions or groove) near4 (gas or vent	IBM_TDB	
		or venting or escape or escaping)	İ	

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Hits	Search Text	DB	Time stamp
296	((alignment or aligning) near2 template) and	USPAT;	2003/01/13 16:19
	(integrated adj circuit or ic or die or mems	US-PGPUB;	
	or mirror or chip)	EPO; JPO;	
17	die near3 (placing or placement or	· '	2003/01/22 15:16
	alignment) near4 template		
		1 ' 1	
		_	
432			2003/01/22 16:14
		,	
	concavity)	1	
	(1)		2002/01/22 16:22
2144		•	2003/01/22 16:23
0.0		_	2003/01/22 16:37
90			2005,01,22 10.5,
		1	
	alighing, hears (complate)	1 '	
	17	(integrated adj circuit or ic or die or mems or mirror or chip) 17 die near3 (placing or placement or alignment) near4 template 432 die near3 (placing or placement or alignment or aligning) near4 (wall or protrusion or projection or hole or depression or concavity) 2144 (chip or ic or wafer or substrate) near3 (placing or placement or alignment or aligning) near4 (template or wall or protrusion or projection or hole or depression or concavity)	(integrated adj circuit or ic or die or mems or mirror or chip) 17 die near3 (placing or placement or alignment) near4 template 432 die near3 (placing or placement or alignment or aligning) near4 (wall or protrusion or projection or hole or depression or concavity) 2144 (chip or ic or wafer or substrate) near3 (placing or placement or alignment or aligning) near4 (template or wall or protrusion or projection or hole or depression or concavity) 2146 (chip or ic or wafer or substrate) near3 (placing or placement or alignment or depression or concavity) 98 (chip or ic or wafer or substrate) near3 (placing or placement or alignment or depression or concavity) 98 (chip or ic or wafer or substrate) near3 (placing or placement or alignment or US-PGPUB;